

Amendments to the Claims

This listing of the claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

Claim 1-9 (Canceled)

Claim 10 (Currently amended) A method for forming an improved field emission display device, comprising the steps of:
 providing a screen; and
 simultaneously applying a phosphor material and a binder material on said screen,
 said binder material holding said phosphor material to said screen, said
 binder material comprising a conductive material.

Claim 11-12 (Canceled)

Claim 13 (Currently amended) A method according to claim 10 wherein said binder material is selected from the group including consisting of: tin(II) 2-ethylhexanoate, tin (IV) isopropoxide, tin(II) oxalate, titanium (IV) ethoxide, zinc 2,4-pentane dionate, zinc acetate, and zinc oxalate.

Claim 14 (Currently amended) A method according to claim 10 wherein said binder material is selected from the group including consisting of: poly(propylene carbonate), poly(propylene carbonate) and poly(ethylene Carbonate).

Claim 15 (Currently amended) A method according to claim [[10]] 21 wherein said semiconductive binder material is selected from the group including consisting of: polyvinyl alcohol, potassium silicate, and ammonium silicate.

Claim 16 (Currently amended) A method according to claim 10 wherein the glass screen is coated with transparent conducting film selected from the group including consisting of: indium tin oxide (ITO), zinc oxide (ZnO), tin oxide (SnO₂) doped with antimony (Sb), cadmium oxide (CdO), and cadmium tin oxide (Cadmium stannate) Cd₂SnO₄.

Claim 17 (Currently amended) A method according to claim 10 wherein the binder material is an organometallic organometallic compound selected from the group including consisting of: cadmium (Cd), titanium (Ti), zinc (Zn)[[.]] tin (Sn), indium (In), antimony (Sb), tungsten (W), niobium (Nb), further comprising the step of heating said binder material to form conductive and/or semiconductive oxides.

Claim 18 (Original) A method according to claim 10 wherein said binder material is transparent.

Claim 19 (Currently amended) A method according to claim 10 wherein said binder material is heated to remove any organics and leave behind a conducting or semiconducting oxide which binds the phosphor particles to each other and to the glass screen.

Claim 20 (Currently amended) A method for forming a field emission display device, comprising:

providing a faceplate comprising a transparent screen having at least one side;
applying a transparent conductor to said side of said screen;
simultaneously applying a layer of phosphor and conductive binder material to
said transparent conductor, said binder material holding said phosphor to
said transparent conductor;

providing a baseplate comprising:

a base electrode;
a plurality of conical field emission cathodes having a base and a tip, the
bases of said field emission cathodes being disposed on said base
electrode; and
a grid electrode disposed proximal proximally to the tips of said field
emission cathodes;

positioning the baseplate proximal said side of said screen so that said baseplate is
spaced apart from said faceplate; and

providing a vacuum gap between said faceplate and said baseplate.

Claim 21 (Currently amended) A method for forming a field emission display device,
comprising:

providing a faceplate comprising a transparent screen having at least one side;
applying a transparent conductor to said side of said screen;
simultaneously applying a layer of phosphor and semiconductive binder material
to said transparent conductor, said binder material holding said phosphor
to said transparent conductor;

providing a baseplate comprising:

a base electrode
a plurality of conical field emission cathodes having a base and a tip, the
bases of said field emission cathodes being disposed on said base
electrode; and
a grid electrode disposed proximal proximally to the tips of said
field emission cathodes;

positioning the baseplate proximal said side of said screen so that said baseplate is
spaced apart from said faceplate; and

providing a vacuum gap between said faceplate and said baseplate.